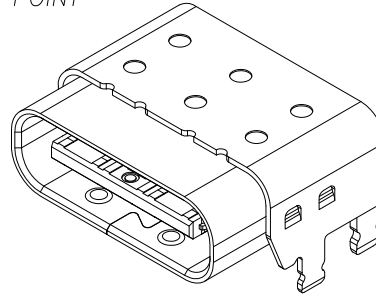
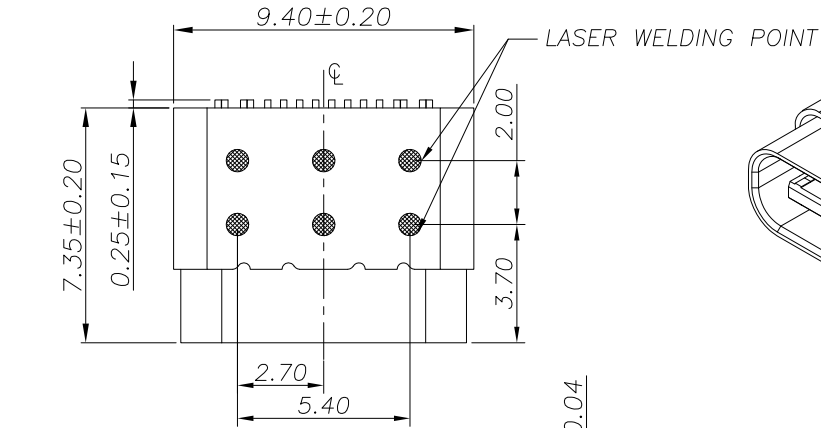


HSF Compliant

REV.	ECN NO.	DESCRIPTION	DRAW	CHECK	APPD.	DATE
A0	—	新版发行	HL.W	BENDEE	BENDEE	22-10-18
A1	ECN230512002	增加产品规格	Dream	BENDEE	BENDEE	2023.05.16

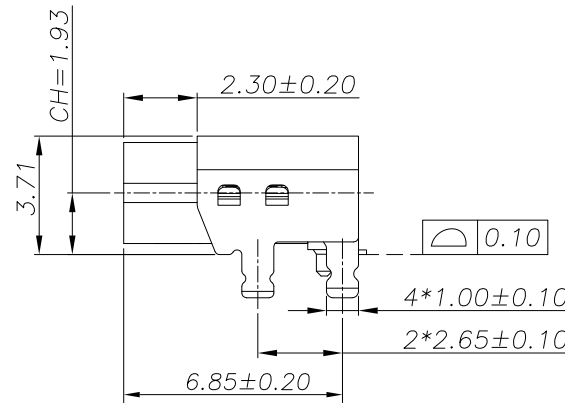
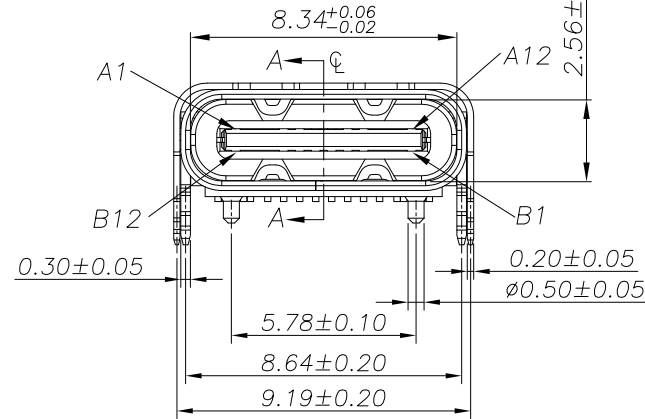
A

A



B

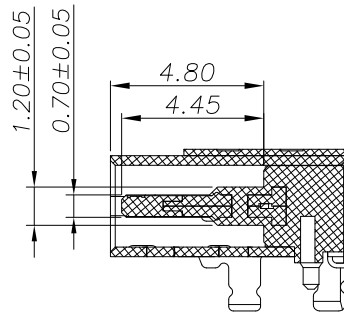
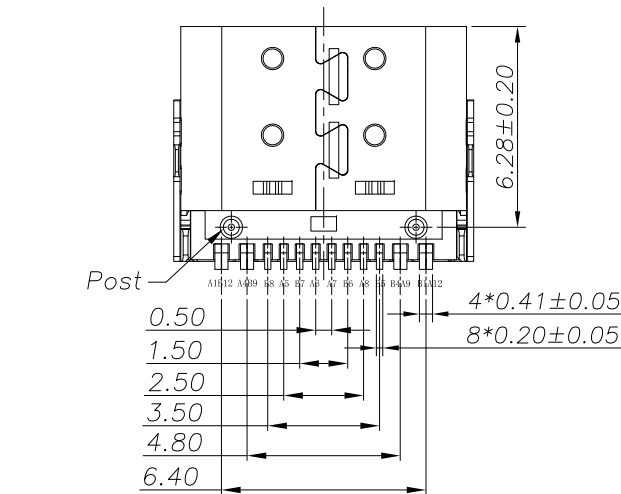
B



料号备注										R=PACK-R0273	
CT	3	F	218	M	XX	R	XX	XX	XX		
53=接触区1U",焊接区1U" 54=接触区3U",焊接区1U" 55=接触区5U",焊接区1U" 56=接触区15U",焊接区1U" 57=接触区30U",焊接区1U" 00=LCP黑色外壳镀镍 (端子C7025, 5A) 01=LCP白色外壳镀镍 (端子C7025, 5A) 02=LCP棕色外壳镀镍 (端子C7025, 5A) 03=LCP黑色外壳镀镍 (端子C18400, 6, 5A) R=ROHS2.0标准 W=无卤+ROHS2.0 B=盐雾24H C=盐雾48H											

C

C



SECTION A-A

D

D

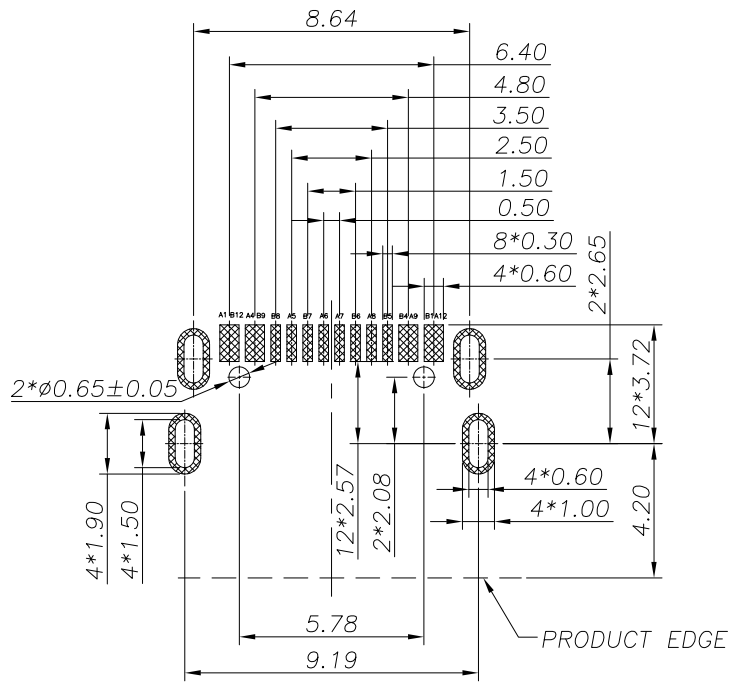


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Dong Guan XingKeJieXin Electronics Co.,Ltd

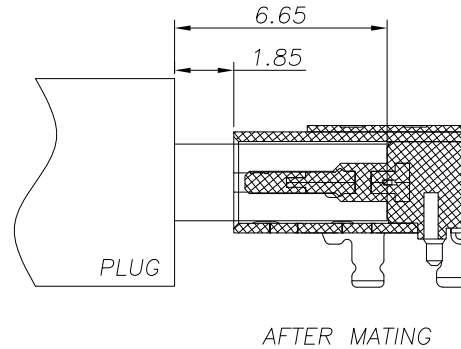
UNLESS OTHERWISE SPECIFIED TOLERANCES		APPROVAL		日期	品名规格	USB TYPE C 单排SMT 16pin CH1.93 L7.35	
X.	+/-	制图	Dream	2023.05.16	规格		
.X	+/-	审核			料号	SEE TABLE	
.XX	+/-	核准			文件位置		
FRACTIONS	+/-	ANGLE OF PROJECTION		字张	工程图号:	DWG-CTCF-218	版本.
ANGLES	+/-			A4			A1
DIMENSIONS				比例	1 : 1	状态码	A
(METRIC)	(MM)			页数	1	OF 2	

HSF Compliant

REV.	ECN NO.	DESCRIPTION	DRAW	CHECK	APPD.	DATE
A0	—	新版发行	HL.W	BENDEE	BENDEE	22-10-18
A1	ECN230512002	增加产品规格	Dream	BENDEE	BENDEE	2023.05.16



RECOMMENDED PCB LAYOUT(TOP VIEW)
THICKNESS 1.2MM;DEFAULT TOLERANCE:±0.05



Specifications:

1.0 Electrical performance:

1.1 Contact resistance: 40mΩ max for initial.
10mΩ change after test. measure at 20mv,
100mA.

1.2 Dielectric withstanding voltage:AC 100V(rms).

1.3 Insulation resistance:100MΩ min.

1.4 Contact current rating:

△A1 5A/6.5A for Vbus pin;1.25A for Vconn and GND
pin;0.25A for all the other pin.

2.0 mechanical performance:

2.1 Mating force:5~20N

2.2 Unmating force:8~20N Initial test,
6~20N After test

2.3 Durability:10,000 cycles.

3.0 Environmental performance:

3.1 Temperature range:

3.2 Operating temperature:−25°to+85°.

3.3 Storage temperature:−20°to+60°.

4.0 Material:

4.1 Housing:LCP Black(HF),UL94−V0.

4.2 Contact:C7025/C18400,T=0.15mm △A1

4.3 Mid-plate: SUS301,T=0.15mm

4.4 Shell:SUS304 T=0.30mm

5.0 Plating specification:

5.1 Contact: Au(see table) plated on contact area,
Gold flash plated on solder
area; Nickel 50u"min underplating over all.

5.2 Shell: Nickel 30u"min plating over all.

料号备注

R=PACK-R0273

CT 3 F 218 M XX R XX XX X

53=接触区1U",焊接区1U"
54=接触区3U",焊接区1U"
55=接触区5U",焊接区1U"
56=接触区15U",焊接区1U"
57=接触区30U",焊接区1U"

00=LCP黑色外壳镀镍
(端子C7025, 5A)
01=LCP白色外壳镀镍
(端子C7025, 5A)
02=LCP橙色外壳镀镍
(端子C7025, 5A)
03=LCP黑色外壳镀镍
(端子C18400, 6.5A)

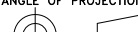
R=ROHS2.0标准
W=无卤+ROHS2.0

D=盐雾24H
C=盐雾48H

△A1



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Dong Guan XingKeJieXin Electronics Co.,Ltd

UNLESS OTHERWISE SPECIFIED TOLERANCES		APPROVAL		日期		品名 规格		USB TYPE C 单排SMT 16pin CH1.93 L7.35									
		制图 Dream		2023.05.16				料号		SEE TABLE							
		审核															
		核准															
X. +/-		METRIC 0.38		文件位置		字张		工程图号:		版本. A1							
.X +/-		0.30															
.XX +/-		0.25															
FRACTIONS +/-		ANGLE OF PROJECTION				A4		DWG-CTCF-218									
ANGLES +/-												2.00°					
DIMENSIONS						比例		1 : 1		状态码		A		页数		2 OF 2	
(METRIC)		(MM)															